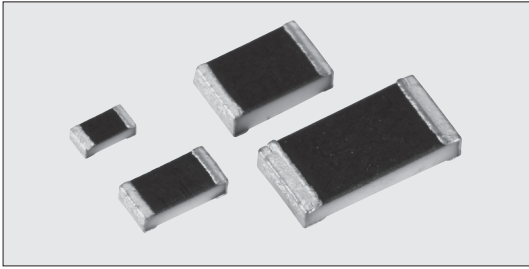


THICK FILM (HIGH RELIABILITY)

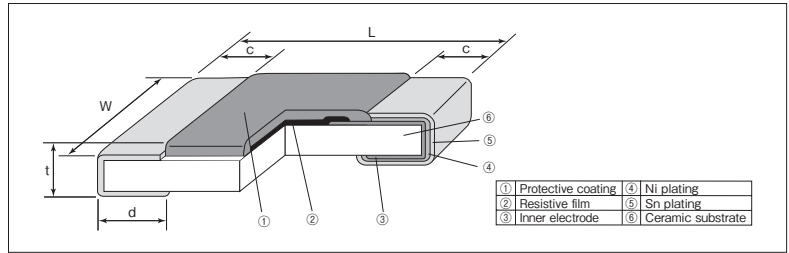


RS73 High Reliability Chip Resistors



Coating color : Black

Construction



Features

- Metal-glaze thick film resistor for surface mounting.
- High precision resistor with T.C.R. $\pm 25 \times 10^{-6}/K$ and tolerance $\pm 0.1\%$.
- High reliability with ΔR of $\pm 0.2\% \sim \pm 0.5\%$ in the Reliability test.
- Suitable for both flow and reflow solderings.
- Products with lead free termination meet EU-RoHS requirements. EU-RoHS regulation is not intended for Pb-glass contained in electrode, resistor element and glass.
- AEC-Q200 Tested.

Applications

- Car electronics, Industrial equipment, Industrial measurement

Reference Standards

IEC 60115-8
JIS C 5201-8
EIAJ RC-2134C

Dimensions

Type (Inch Size Code)	Dimensions (mm)					Weight (g) (1000pcs)
	L	W	c	d	t	
1E (0402)	1.0 ^{+0.1} _{-0.05}	0.5±0.05	0.2±0.1	0.25 ^{+0.05} _{-0.1}	0.35±0.05	0.68
1J (0603)	1.6±0.2	0.8±0.1	0.2±0.1	0.3±0.1	0.45±0.1	2.14
2A (0805)	2.0±0.2	1.25±0.1	0.25±0.15	0.3 ^{+0.2} _{-0.1}	0.5±0.1	4.54
2B (1206)	3.2±0.2	1.6±0.2	0.35±0.15	0.4 ^{+0.2} _{-0.1}	0.6±0.1	9.14

Type Designation

Example

Product Code	Power Rating	Terminal Surface Material	Taping	Nominal Resistance	Resistance Tolerance
RS73F RS73G	1E : 0.125W 1J : 0.2W 2A : 0.25W 2B : 0.33W	T : Sn	TPL·TP : 2mm pitch punch paper TD : 4mm pitch punch paper BK : Bulk	4 digits	B : ±0.1% C : ±0.25% D : ±0.5% F : ±1.0%

Contact us when you have control request for environmental hazardous material other than the substance specified by EU-RoHS.

For further information on taping, please refer to APPENDIX C on the back pages.

Ratings

Type	Power Rating	Rated Ambient Temp.	Rated Terminal Part Temp.	T.C.R. ($\times 10^{-6}/K$)	Resistance Range (Ω) ^{※2}				Max. Working Voltage	Max. Overload Voltage	Packaging & Q'ty/Reel (pcs)	
					B: ±0.1% E24·E96	C: ±0.25% E24·E96	D: ±0.5% E24·E96	F: ±1.0% E24·E96			TPL·TP	TD
RS73F1E	0.125W	85°C	125°C	±25 ^{※1}	300~100k	300~1M	300~1M	300~1M	75V	100V	TPL:20,000 TP:10,000	—
RS73G1E				±50								
RS73F1J	0.2W			±25 ^{※1}	10~1M	10~1M	10~1M	10~1M	100V	150V	—	5,000
RS73G1J				±50								
RS73F2A	0.25W			±25 ^{※1}	10~3M	10~6.8M	10~10M	10~10M	150V	300V	—	5,000
RS73G2A				±50								
RS73F2B	0.33W	±25 ^{※1}	10~5.1M	10~5.1M	10~10M	10~10M	200V	400V	—	5,000		
RS73G2B		±50										

Operating Temperature Range : $-55^{\circ}C \sim +155^{\circ}C$

Rated voltage = $\sqrt{\text{Power Rating} \times \text{Resistance value}}$ or Max. working voltage, whichever is lower.

For flat chip jumper resistor, please refer to RK73Z series.

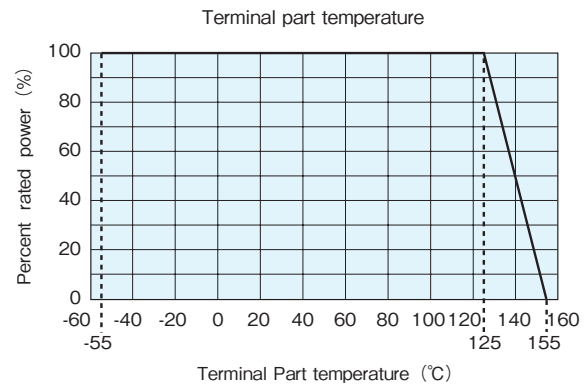
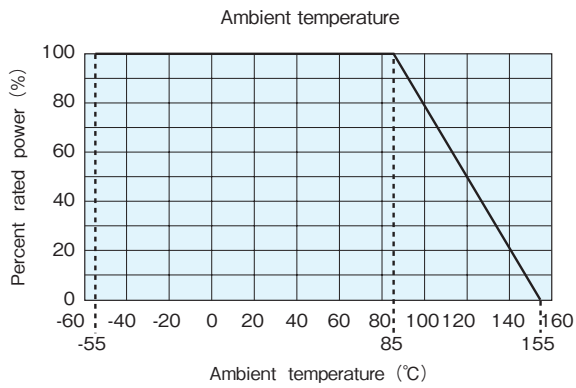
※1 Measurement Temperature: $+25^{\circ}C / +125^{\circ}C$. Cold T.C.R. ($-55^{\circ}C / +25^{\circ}C$) is $-50 \sim +25 \times 10^{-6}/K$.

※2 Please inquire of us about E192.

If any questions arise whether to use the "Rated Ambient Temperature" or the "Rated Terminal Part Temperature" in your usage conditions, please give priority to the "Rated Terminal Part Temperature".

For more details, please refer to "Introduction of the derating curves based on the terminal part temperature" on the beginning of our catalog.

Derating Curve

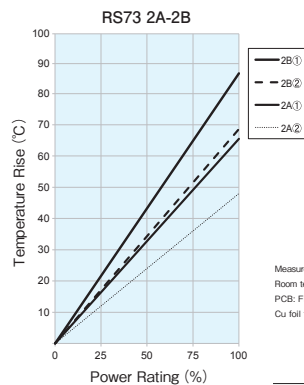
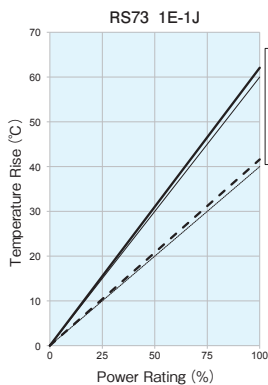


For resistors operated at an ambient temperature of 85°C or higher, the power shall be derated in accordance with the above derating curve.

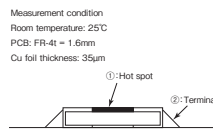
When the terminal part temperature of the resistor exceeds the rated terminal part temperature shown above, the power shall be derated according to the derating curve.

※Please refer to "Introduction of the derating curves based on the terminal part temperature" on the beginning of our catalog before use.

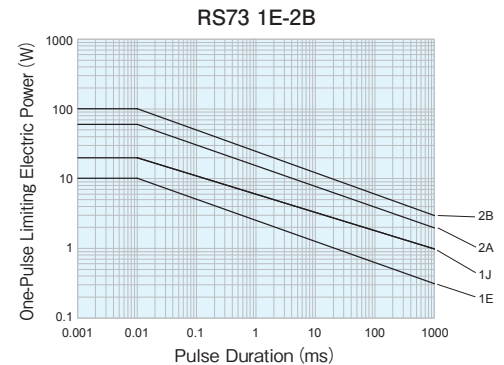
Temperature Rise



Regarding the temperature rise, the value of the temperature varies per conditions and board for use since the temperature is measured under our measuring conditions.



One-Pulse Limiting Electric Power



The maximum applicable voltage is equal to the max. overload voltage. Please ask us about the resistance characteristic of continuous applied pulse. The pulse endurance values are not assured values, so be sure to check the products on actual equipment when you use them.

Performance

Test Items	Performance Requirements $\Delta R \pm (\% + 0.05 \%)$		Test Methods
	Limit	Typical	
Resistance	Within specified tolerance	—	25°C
T.C.R.	Within specified T.C.R.	—	+25°C / -55°C and +25°C / +125°C
Overload (Short time)	0.2	0.03	Rated voltage $\times 2.5$ for 5s
Resistance to soldering heat	0.2	0.1	260°C $\pm 5^\circ\text{C}$, 10s ± 1 s
Rapid change of temperature	0.2 : 1E (300Ω $\leq R \leq 20\text{k}\Omega$) 1J (10Ω $\leq R \leq 1\text{M}\Omega$) 2A, 2B (10Ω $\leq R \leq 10\text{M}\Omega$) 0.4 : others	0.05 : 1E (300Ω $\leq R \leq 20\text{k}\Omega$) 1J (10Ω $\leq R \leq 1\text{M}\Omega$) 2A, 2B (10Ω $\leq R \leq 10\text{M}\Omega$) 0.2 : others	-55°C (30min.) / +125°C (30min.) 1000 cycles
Moisture resistance	0.2 : 1E (300Ω $\leq R \leq 10\text{k}\Omega$) 1J (10Ω $\leq R \leq 200\text{k}\Omega$) 2A, 2B (10Ω $\leq R \leq 10\text{M}\Omega$) 0.4~0.5 : others	0.04 : 1E (300Ω $\leq R \leq 10\text{k}\Omega$) 1J (10Ω $\leq R \leq 200\text{k}\Omega$) 2A, 2B (10Ω $\leq R \leq 10\text{M}\Omega$) 0.08 : others	40°C $\pm 2^\circ\text{C}$, 90%~95%RH, 1000h 1.5h ON / 0.5h OFF cycle
Endurance at 85°C or rated terminal part temperature	0.2 : 1E (300Ω $\leq R \leq 20\text{k}\Omega$) 1J (10Ω $\leq R \leq 1\text{M}\Omega$) 2A, 2B (10Ω $\leq R \leq 10\text{M}\Omega$) 0.4 : others	0.05 : 1E (300Ω $\leq R \leq 20\text{k}\Omega$) 1J (10Ω $\leq R \leq 1\text{M}\Omega$) 2A, 2B (10Ω $\leq R \leq 10\text{M}\Omega$) 0.2 : others	85°C $\pm 2^\circ\text{C}$ or rated terminal part temperature $\pm 2^\circ\text{C}$ 1000h 1.5h ON / 0.5h OFF cycle
High temperature exposure	0.2 : 1E (300Ω $\leq R \leq 10\text{k}\Omega$) 1J (10Ω $\leq R \leq 200\text{k}\Omega$) 2A, 2B (10Ω $\leq R \leq 100\text{k}\Omega$) 0.4~0.5 : others	0.1 : 1E (300Ω $\leq R \leq 10\text{k}\Omega$) 1J (10Ω $\leq R \leq 200\text{k}\Omega$) 2A, 2B (10Ω $\leq R \leq 100\text{k}\Omega$) 0.2~0.3 : others	+155°C, 1000h

Precautions for Use

- The substrate of chip resistors is alumina. Cracks may occur at the connection of solder (solder fillet portion) due to the difference of the coefficient of thermal expansion from a mounting board when heat stress like heat cycle, etc. are repeatedly given to them. Care should be taken to the occurrence of the cracks when the change in ambient temperature or ON/OFF of load is repeated. The occurrence of the crack by heat stress may be influenced by the size of a pad, solder volume, heat radiation of mounting board etc., so please pay careful attention to designing when a big change in ambient temperature and conditions for use like ON/OFF of load can be assumed.